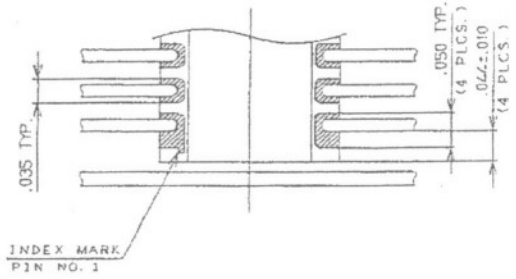
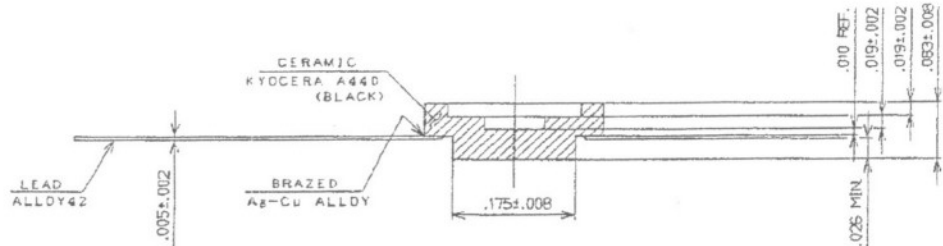
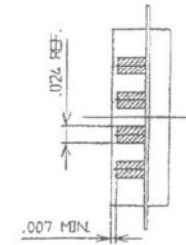
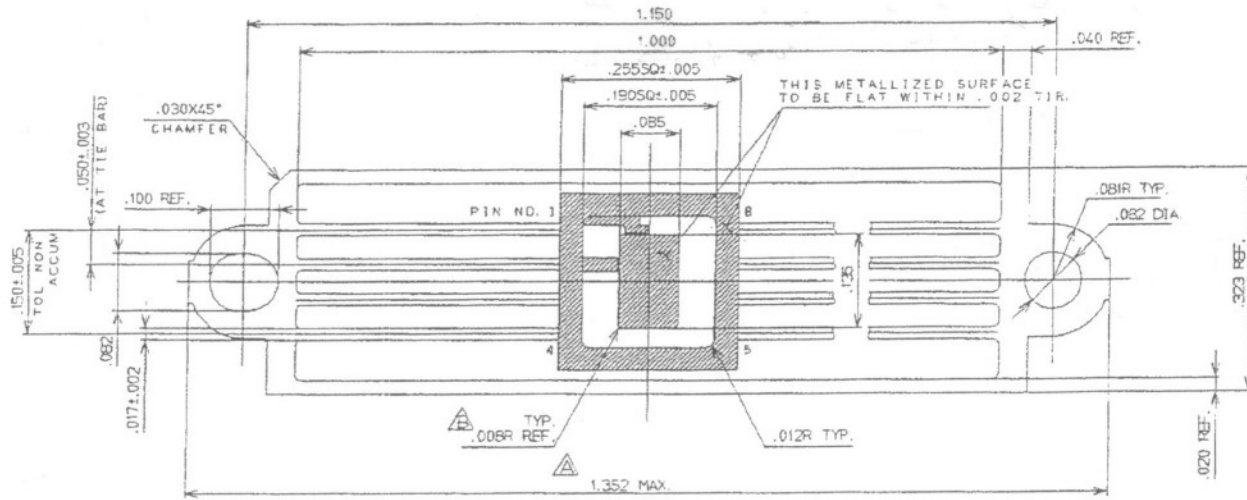


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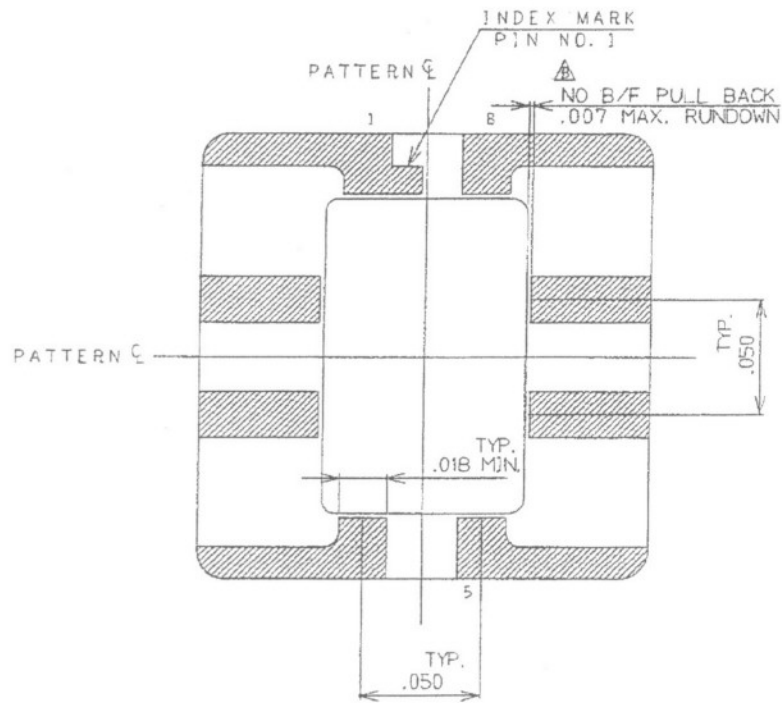


- NOTES:
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
 2. SEAL AREA TO BE METALLIZED.
 3. DIE ATTACH AREA TO BE METALLIZED.
 4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
 5. LEAD RESISTANCE: 0.2Ω MAX.
 6. THIS PACKAGE SHALL CERTIFY TO MEET THE STYLE CHARACTERIZATION TESTING REQUIREMENTS LISTED IN MIL-1-38535, TABLE B

MODIFICATION CHANGED: NOTE 6 II → I ADDED: .006R REF. TYP., NOTE 6 ADDED: 1.352 MAX. CHANGED		SEP. 8 '91 K. J. A. F. / S. F. T. A. SEP. 7 '91 K. J. H. S. / S. F. T. A. JUN. 23 '90 S. F. T. C. T. A.	NAME 8 LEAD FLAT PACKAGE SCALE $\frac{B}{1}$ MATERIAL AS INDICATED	TOLERANCE UNLESS OTHERWISE SPECIFIED $\pm .005$ UNLESS SPECIFIED OTHERWISE	FB008ABD36-1 B=0 DRAWN / CHECKED / APPROVED / DATE S. F. A. K. W. T. A. DEC. 02 '91
		DATE DRAWN / CHECKED / APPROVED		KYOCERA CORPORATION KYOTO JAPAN	KD-93D36-C-JM



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BONDING PATTERN

					NAME 8 LEAD FLAT PACKAGE	TOLERANCES: UNLESS OTHERWISE SPECIFIED	DRAWN S. F.	CHECKED A. F.	APPROVED K. M. T. A.	DATE DEC. 02, '93
					SCALE 20/1	MATERIAL				
ADDED: NO B/F PULL BACK, .007 MAX. RUNDOWN					SEP. 7, '94	K. I.	H. S./S. F.	T. A.		
CHANGE					DATE	DRAWN	CHECKED	APPROVED		
					KYOCERA	KYOCERA CORPORATION KYOTO JAPAN		KD-93D36-C-JMI		

